

7. (Twice Amended) A method of manufacturing a semiconductor device, comprising, sequentially:

joining a ball formed at a tip end of a bonding wire to a first conductive layer as a first contact;

joining a first part of said bonding wire to a second conductive layer;

mechanically deforming a second part of said bonding wire, while said first part of said bonding wire is joined to the second conductive layer, so that said bonding wire is folded onto said first part of said bonding wire directly opposite said second conductive layer; and

joining said second part of said bonding wire to said first part of said bonding wire on said second conductive layer.

10. (Twice Amended) The method of manufacturing a semiconductor device according to claim 7, wherein

said bonding wire is held by a bonding tool; and

mechanically deforming said bonding wire includes mechanically deforming said bonding wire on said second conductive layer by moving said bonding tool with said bonding wire joined to said second conductive layer.